

P/1071-1453

METHOD OF BONDING A CONDUCTIVE ADHESIVE AND AN ELECTRODE, AND A BONDED STRUCTURE OBTAINED THEREBY

ABSTRACT OF THE DISCLOSURE

5 The present invention relates to a method of bonding a conductive adhesive and an electrode together, which is capable of obtaining electrical bonding between a conductive electrode and an electrode. In this method, a conductive adhesive containing a conductive filler and an
10 organic binder is coated on an electrode having a layer formed thereon by plating a low-melting-point material, and then heated to cure the organic binder and melt the plated layer on the electrode. As a result, the conductive filler contained in the adhesive enters the
15 plated layer to obtain strong bonding between the plated layer and the conductive filler.